



新應材股份有限公司

Advanced Echem Materials Company Ltd.

Stock code : 4749

Investor Conference



Safe Harbor Notice

- AEMC's statements of its current expectations are forward-looking statements subject to significant risks and uncertainties and actual results may differ materially from those contained in the forward-looking statements.
- AEMC makes no representation or warranty regarding such forward-looking statements. Except as required by law, AEMC undertakes no obligation to update any forward-looking statements, whether as a result of new information, future events, or otherwise.

Agenda

- Company Overview
- Main Products and Markets
- Product Roadmap
- Financial Highlights
- ESG Performance
- Appendix

Our Mission and Vision

Mission

Establish upstream and downstream supply chains.

Our mission is to establish Taiwan's independent technology in specialty chemicals for advanced semiconductor processes and through collaboration, enhance the global competitiveness of the local specialized materials industry, both upstream and downstream.

Vision

Expand the variety of semiconductor materials and increase market share.

Our vision is to enhance Synthesis, Purification, Formulation, and process technologies to meet customer needs, assist in yield improvement deliver exceptional added value, and become an innovative specialty chemical company with global competitiveness.

Awards

- **TSMC Excellent Performance Award, 2022**
Excellent Material [Development](#) and [Production Support](#) in Lithography Materials.
- **National Industrial Innovation Award, 2023**

AEMC Strategic Portfolio Map

- Core Vision : Meet customer needs, improve yield, create exceptional value, and become a globally competitive innovative specialty materials company.
- Leveraging materials science and R&D capabilities, we focus on high-tech, high-barrier industries and invest strategically in critical materials and technologies to build sustainable competitive advantages.

Semiconductor Advanced Process Materials

AEMC

Photolithography Specialty Materials

- Expertise: Synthesis | Purification | Formulation

SCIWIN

Strategic Raw Materials R&D

- Expertise: Synthesis
- Shareholding: 70%

Oleader

Strategic Raw Materials Manufacturing

- Expertise: Synthesis
- Shareholding: 40% Common Shares + 13.34% Preferred Shares

Full Chain

Semiconductor Specialty Gases R&D and Manufacturing

- Expertise: Purification
- Shareholding: 15.74% (in Progress)

Semiconductor Advanced Packaging Materials

AEMC

Photolithography Specialty Materials

- Expertise: Synthesis | Purification | Formulation

e-Ray

HPC (AI & Server Applications), CCL Resin Materials

- Expertise: Synthesis | Formulation
- Shareholding: 25.08%

APTT

LEAP Advanced Packaging Tapes

- Expertise: Formulation | Coating
- Shareholding: 26.87%

About AEMC



Paid-in Capital : NT\$947M / US\$31.6M
Number of Employees : 474 (2026.06)
R&D Personnel : 140 (2026.06)

Locations

Taoyuan Factory : HQ with R&D Center, Display Photo Resists, Optical Component Materials
Tainan Factory : Semiconductor Specialty Chemicals
Kaohsiung Factory P1, P2 (Under Qualification) : Semiconductor Specialty Chemicals

Main Products

- Specialty Materials for Semiconductors
Advanced Process Materials
Advanced Packaging Materials
Optical Component Materials
- Specialty Materials for Displays
Display Photoresist

Invested Companies

- AEMC JAPAN (100%)
- AEMC USA (100%)
- **SCIWIN Laboratories** (70%)
- **Oleader Technologies** (40%+Preferred shares 13.34%) Equity investment
- **e-Ray Technology** (25.08 %) Equity investment
- **Advanced Pao Trusval Technology** (26.87 %) Equity investment
- **Full Chain Materials** (15.74%)(in progress) Equity investment

About AEMC



2003

Photoresist for Display

2014

Materials for Semiconductor Optical Components

2018

Materials for Advanced Semiconductor Processes

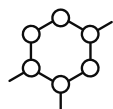
2025

Photoresist for Advanced Semiconductor Processes

2026

Materials for Advanced Packaging

Main Products



Semiconductor Specialty Chemicals

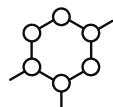
-Advanced Lithography Process

- Rinse
- EBR
- BARC
- Cleaner

-Advanced Packaging Material

-Optical Component

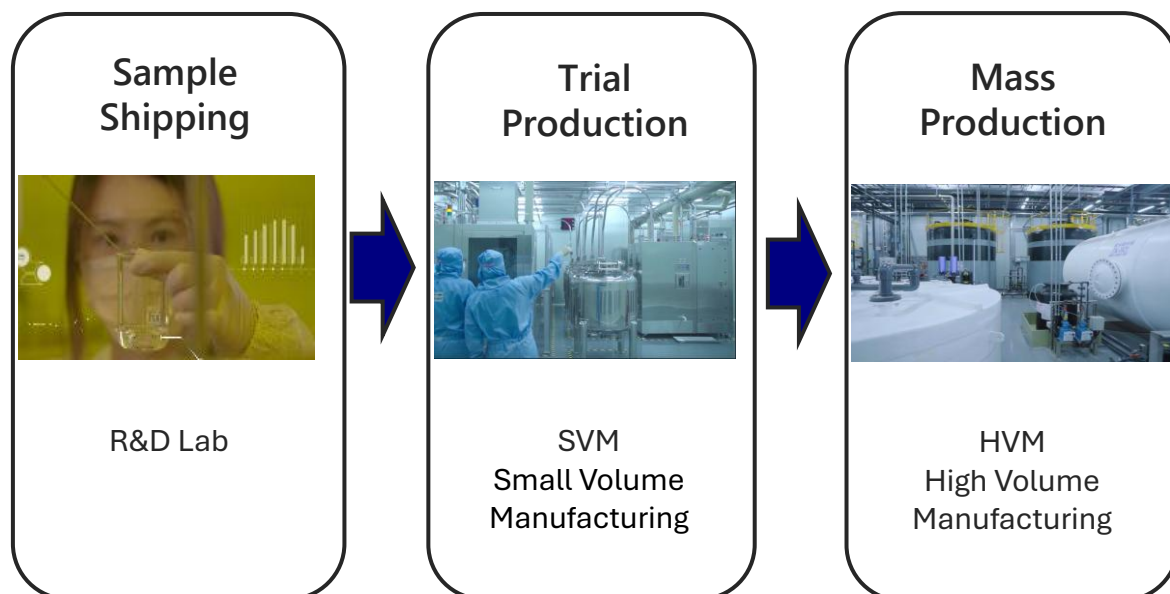
- Image Sensor Material
- Micro-Optical Component Material



Display Specialty Chemicals

-Display Photoresist

R&D and Production Sites



New Factory in Taoyuan (Longtan Science Park)

R&D Center, Semiconductor Specialty Materials

Scheduled for Completion in 2028

Taoyuan Factory

Display Photoresist

Optical Component Materials

Tainan Factory

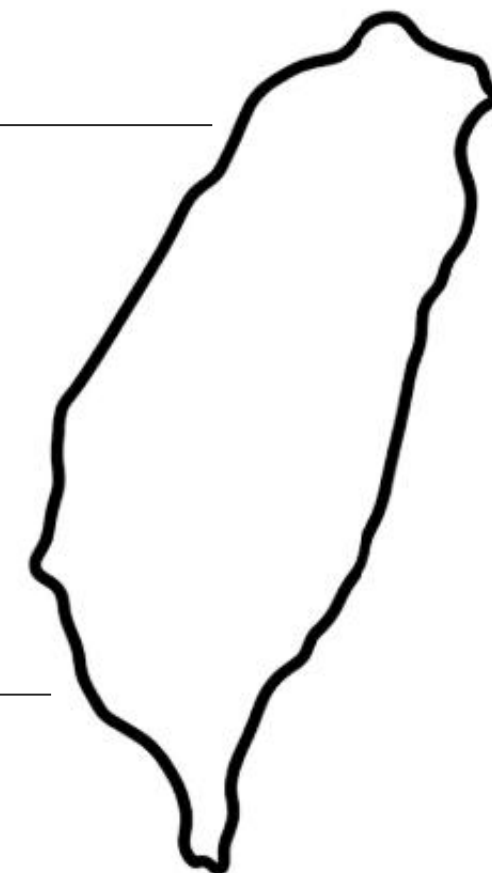
Semiconductor

Specialty Chemicals

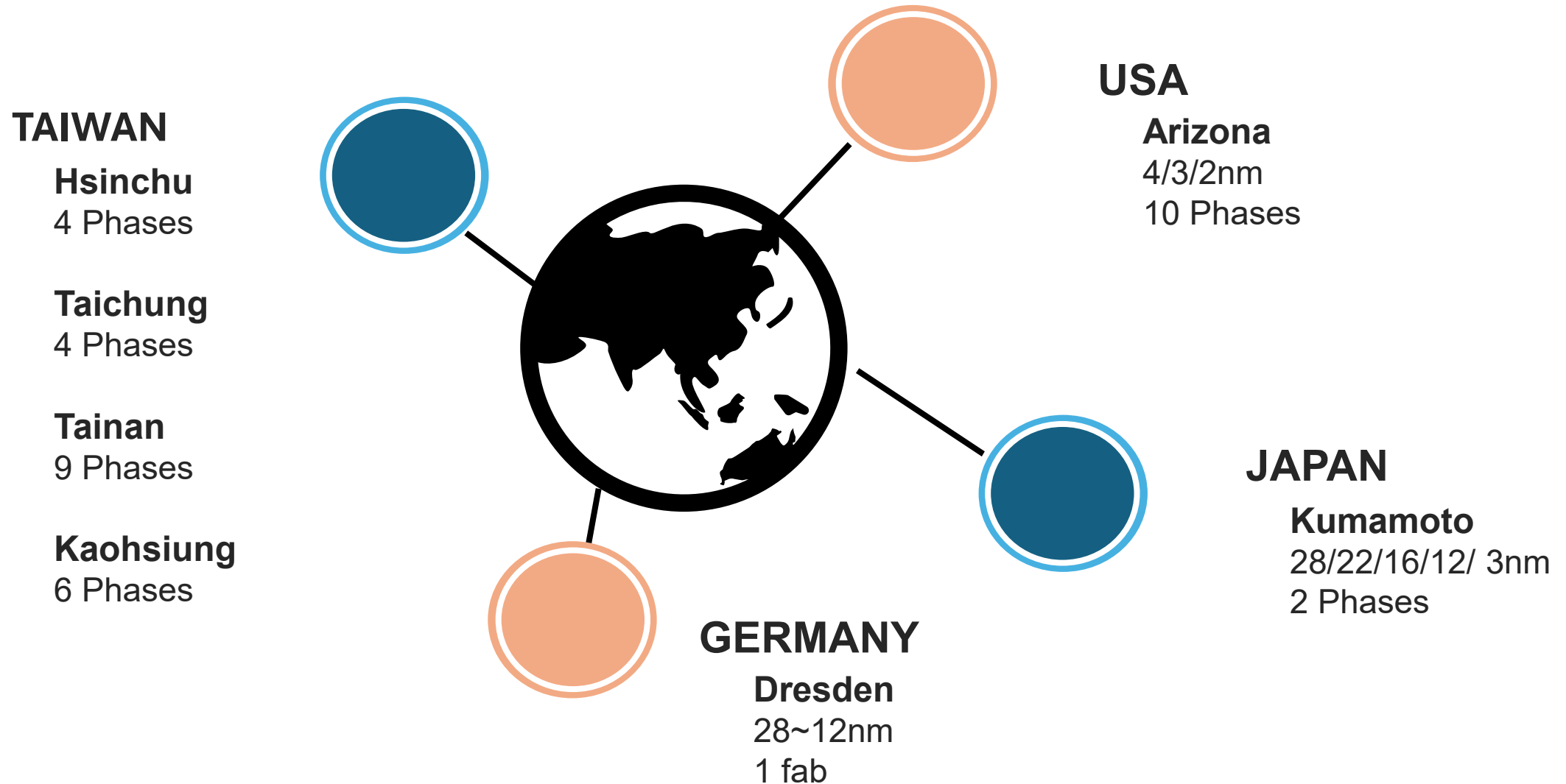
Kaohsiung Factory

Semiconductor Specialty

Chemicals



Major Customer's Advanced Process Capacity Roadmap (2025~)



Source: Economic Daily News, Digitimes, and other media reports.

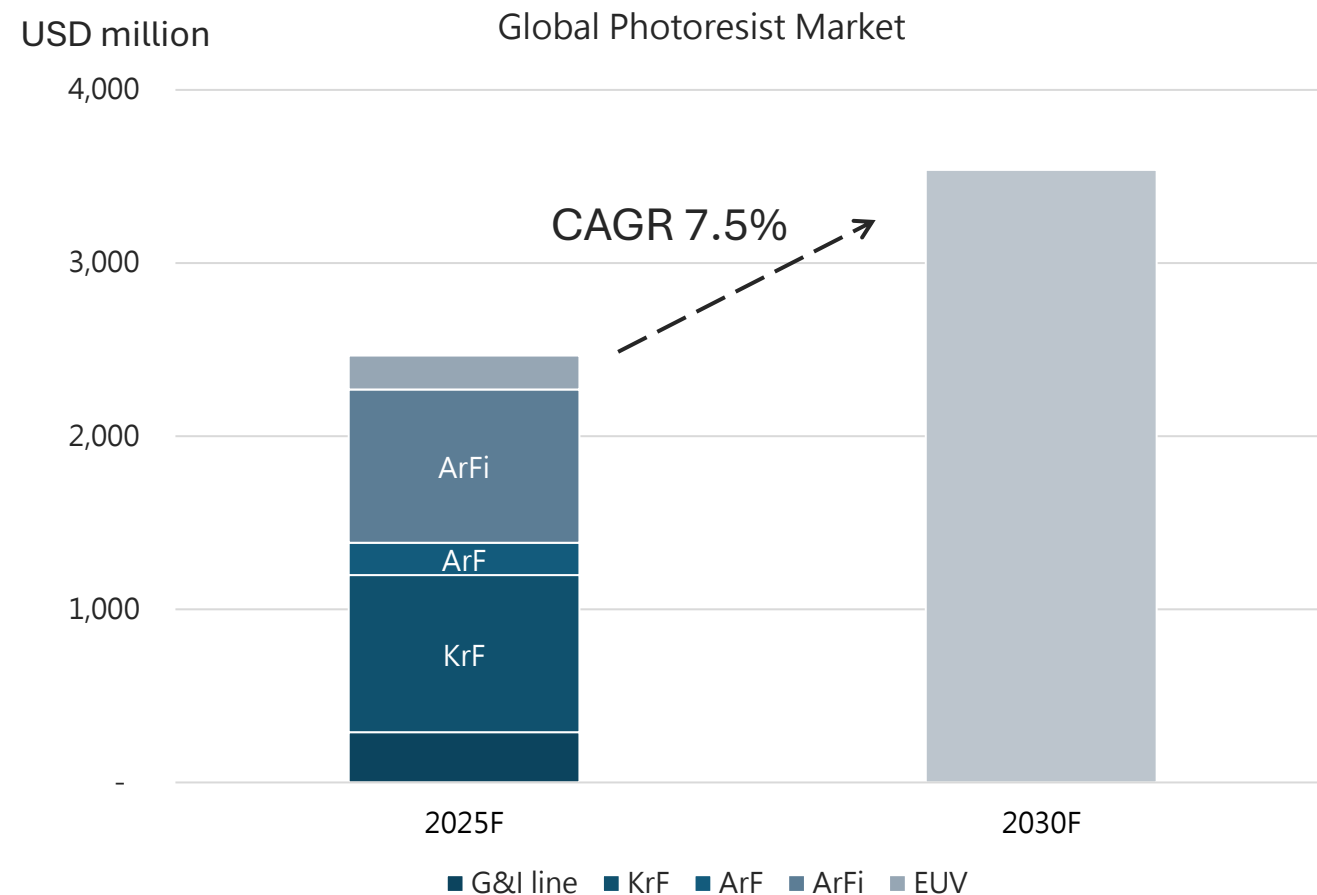
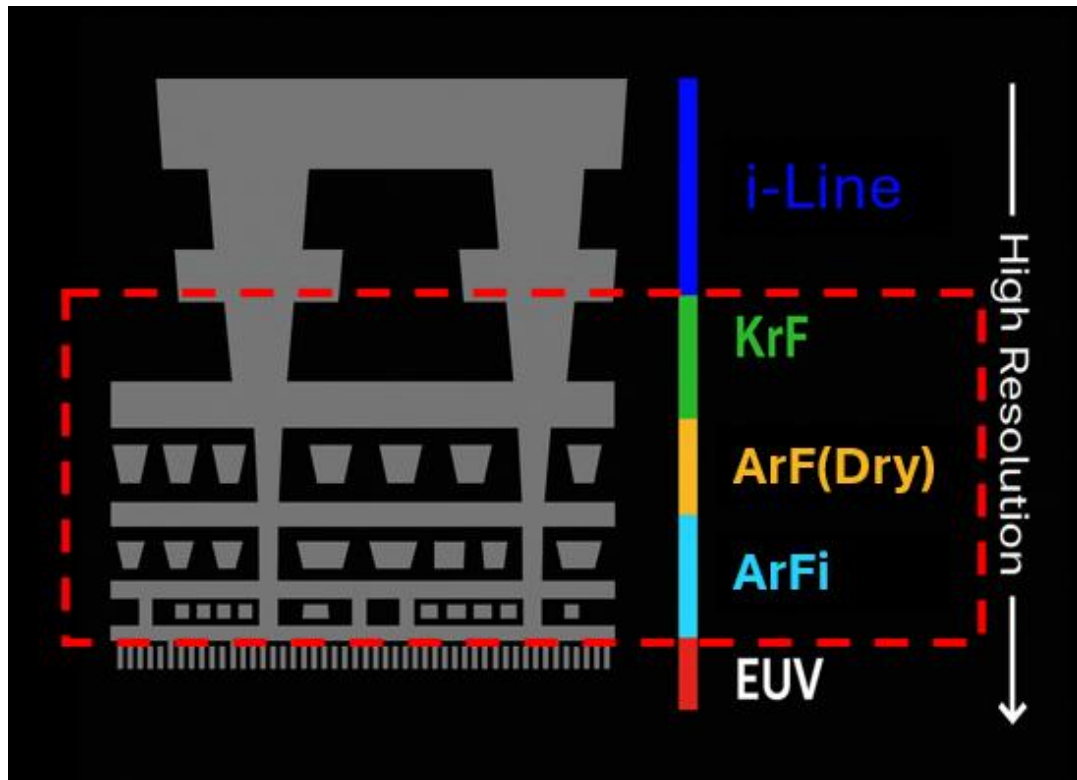
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R&D Roadmap

Application Field	Mass Production	Verification	Developing
Advanced Microlithography Materials	- Rinse Material (表面改質劑) - BARC (底部抗反射層) - EBR (洗邊劑) - Cleaner (清洗劑)	- Rinse Material for next node - BARC for next node - EBR for next node - Cleaner for next node - DUV Photoresist (KrF)	- Bottom Layer for next node - Advanced BARC - Protection Layer - DUV Photoresist (ArF)
Advanced Packaging Materials	- Temporary Protection Layer - Plasma Dicing Glue	- Protection Layer for SolC - KrF BARC - Cleaner - Protection Glue for CPO - Leveling Layer	- High AR Photoresist - Packaging Glue - Photoresist for Fine pitch QFN
Optical Element Materials	- Photoresists (光阻劑) - Flat Layer (平坦層) - Color Filter Layer (濾光層) - Light-cut Layer (遮光層) - Lift-off Layer(離型層)	- DUV Photoresist (ArF) - Stripper - Lift-off Layer for next node - ArF BARC - Adhesion Layer	- Leveling Layer - Microlens Materials

Photoresist Market

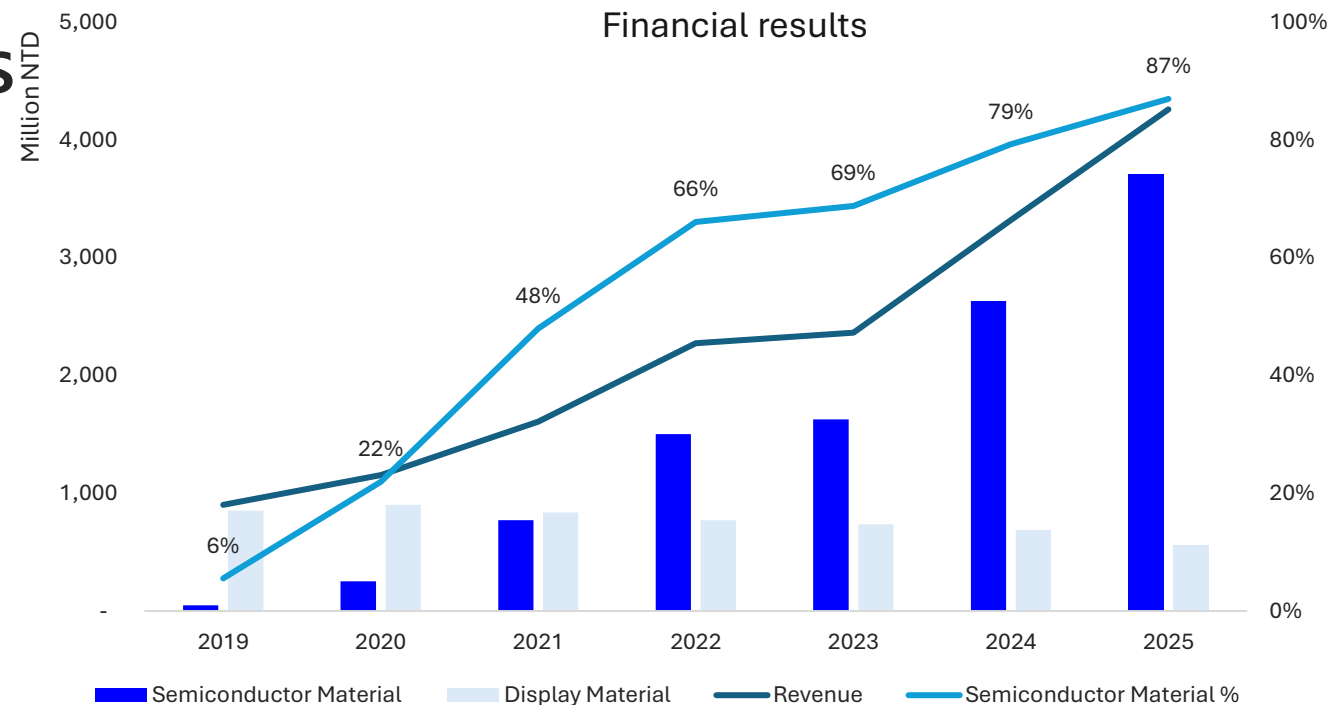


Source: TECHCET(2021) 、WSTS(2024) 、Deloitte(2025) 、 Estimate by Company

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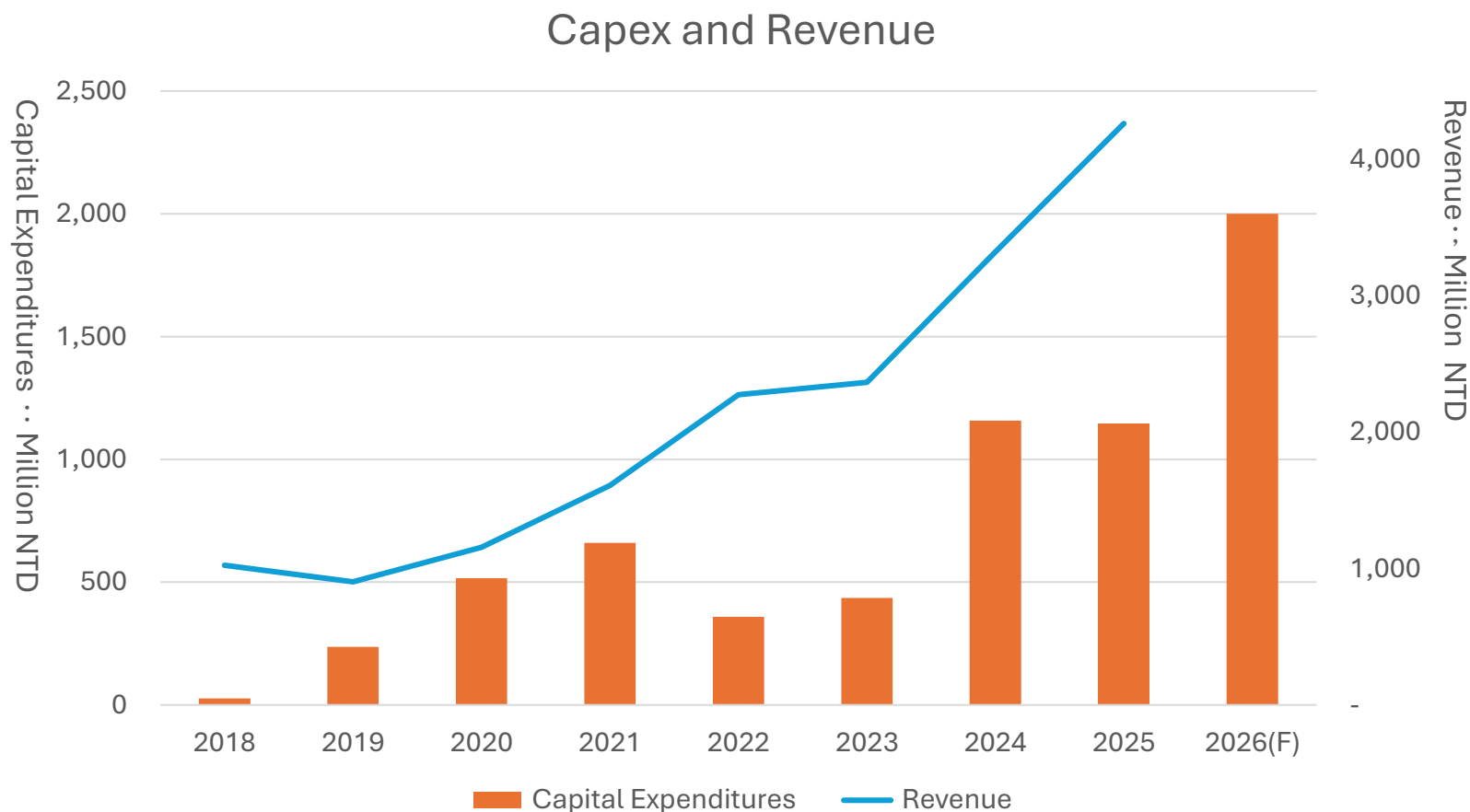
Financial Highlights



Year	2021	2022	2023	2024	2025	1Q2026	2Q2026
Revenue	1,609	2,274	2,364	3,322	4,262	1,246	1,233
Semiconductor Material	773	1,503	1,627	2,634	3,708	1,108	1,110
Display Material	836	771	737	688	554	138	123
Gross Profit	422	723	694	1,204	1,835	566	549
Gross Margin	26.2%	31.8%	29.4%	36.3%	43.1%	45.4%	44.5%
Operating Income	53	295	225	587	1,061	337	286
Net Income Attributable to the Parent Company	122	404	318	698	1,044	340	304
EPS (NT\$)	1.62	5.01	3.91	8.50	11.33	3.66	3.28

Capital Expenditures

Since 2018, AEMC has invested over NTD 4 billion in capital expenditures to support its transition into semiconductor materials development by the end of 2025.



ESG Performance

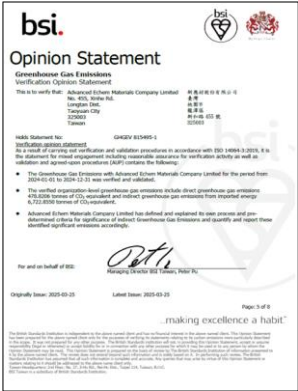


Energy Efficiency and Carbon Reduction Talent Sustainability

Social Engagement

Corporate Governance

Friendly Workplace



Integrating corporate initiatives with employee engagement to continuously enhance actions in public welfare and environmental sustainability.

Completed greenhouse gas inventory ahead of regulatory schedule and obtained a statement from a third-party verification body in 2024&2025.

Awarded a certificate of appreciation by a major wafer foundry customer for the 'Supplier Energy Saving and Carbon Reduction Guidance Program

Established the 'AEMC Scholarship'

Founded the 'New Immigrant Children Scholarship'

Actively participated in 'Industry-Academia Cooperation

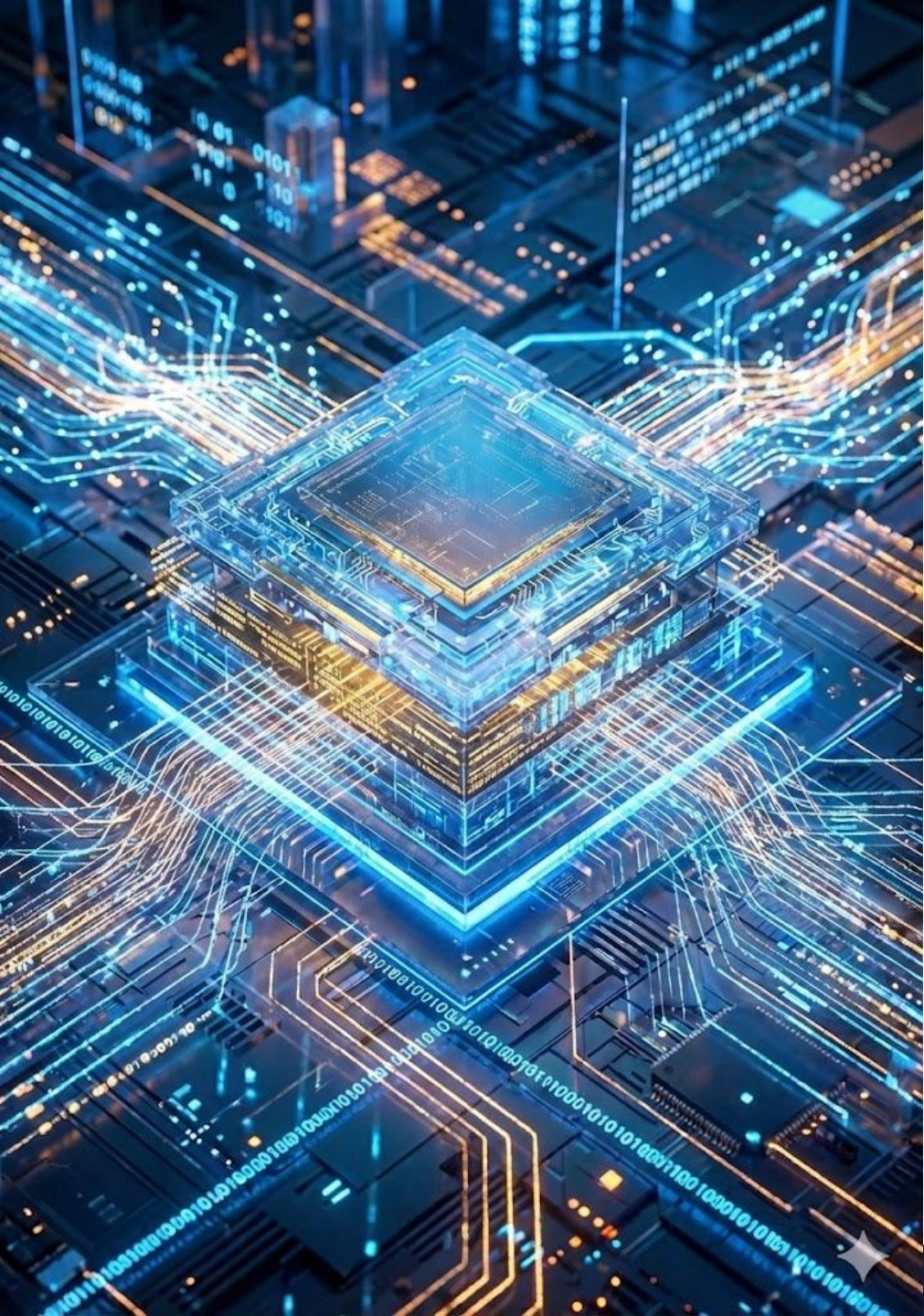
4 Independent directors, accounting for more than 44%

2 Female directors, accounting for more than 22%

The first Sustainability Report was issued in 2025 and will be published regularly on an annual basis.

Recognized as a Happy Enterprise Gold Award Winner for Three Consecutive Years

The company places great emphasis on gender equality and diversified development, with female employees and female managers each accounting for more than 30% of the workforce.



Feedback & Discussion Thank you for listening.

For further information, please visit our website at:
<https://www.aemc.com.tw/>

Contact Investor Relations at:
ir@aemc.com.tw

Income Statement

NT\$ million	2Q26	1Q26	2Q25	QOQ	YOY
Net Revenue / Net Sales	1,233	1,246	1,153	-1.0%	6.9%
Gross Profit	549	566	533	-3.0%	3.0%
Gross Margin	44.5%	45.4%	46.2%	-1.9%	-3.7%
Operating Expenses	263	229	176	15.0%	49.8%
Operating Profit	286	337	358	-15.2%	-20.0%
Operating Margin	23.2%	27.1%	31.0%	-14.3%	-25.2%
Non-operating Income and Expenses	75	73	(10)	2.5%	-826.2%
Net Income Attributable to the Parent Company	304	340	285	-10.4%	6.9%
EPS (NT\$)	3.28	3.66	3.07	-10.4%	6.8%

Balance Sheet

NT\$ million	2Q26		1Q26		2Q25	
	Amount	%	Amount	%	Amount	%
Cash and Cash Equivalents	1,887	13.0%	865	8.0%	2,185	21.6%
Accounts Receivable	684	4.7%	615	5.7%	523	5.2%
Property, Plant and Equipment	4,546	31.2%	3,881	35.7%	3,017	29.8%
Total Assets	14,569	100.0%	10,881	100.0%	10,123	100.0%
Current Liabilities	1,791	12.3%	1,679	15.4%	1,367	13.5%
Long-term Borrowings	300	2.1%	-	0.0%	-	0.0%
Total Liabilities	4,212	28.9%	1,931	17.7%	1,525	15.1%
Total Shareholders' Equity	10,349	71.0%	8,942	82.2%	8,588	84.8%
Key Financial Ratios						
Current Ratio	445%		332%		451%	
Debt Ratio	29%		18%		15%	
Net Asset Value Per Share(NT\$)	111.49		96.42		92.61	

Cash Flow Statement

NT\$ million	2Q26	1Q26	4Q25
Beginning Cash Balance	893	965	1,778
Cash Flows from Operating Activities	217	219	215
Depreciation and Amortization Expenses	78	77	76
Capital Expenditures	(748)	(192)	(698)
Long-term Borrowings	300	0	0
Ending Cash Balance	1,887	893	965
Free Cash Flow	(531)	27	(483)

Note: Free Cash Flow = Cash Flows from Operating Activities – Capital Expenditures

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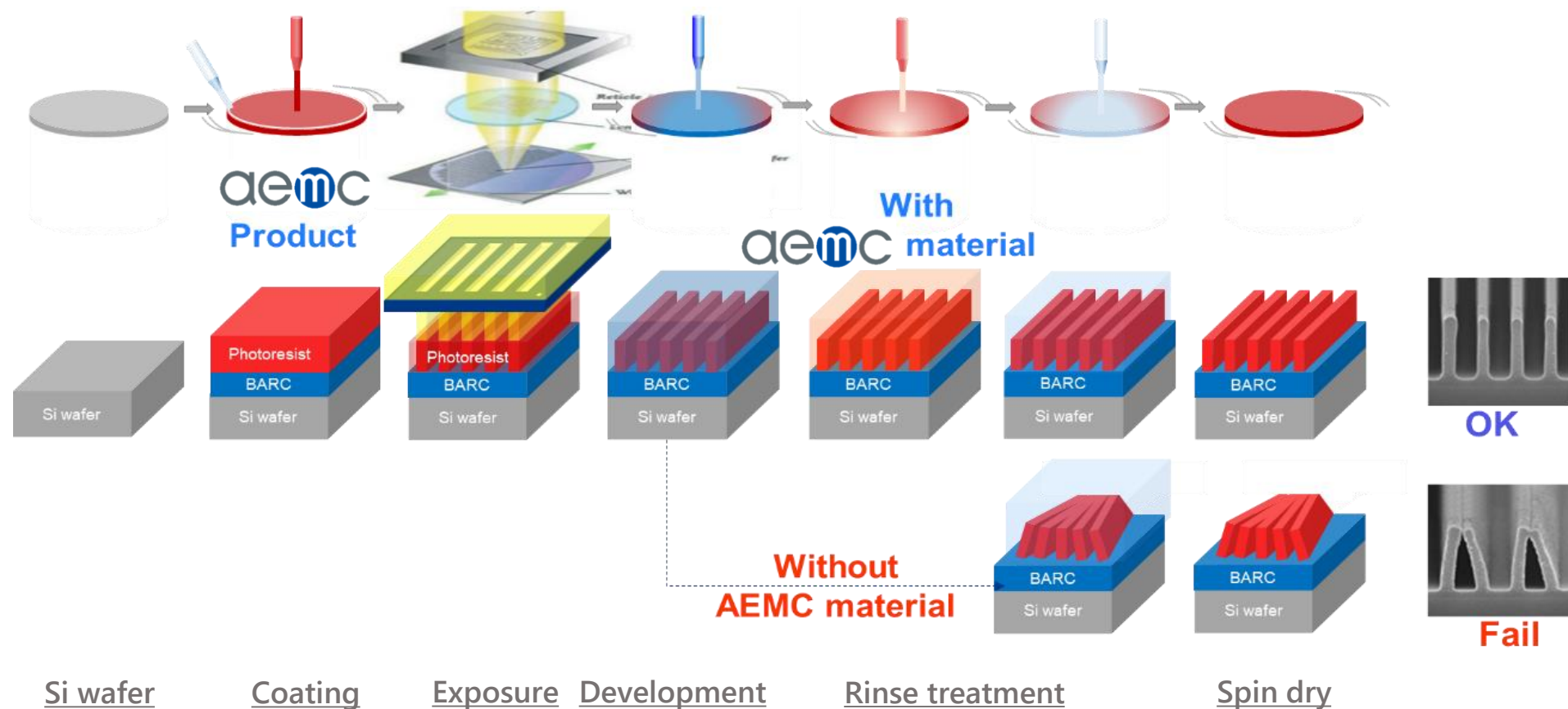
Lithography Materials for Advanced Semiconductor Processes

aemc
Products

■ BARC
■ EBR

■ Rinse Material

■ Cleaner
(Pipeline and Equipment)



Key Material for Advanced Semiconductor Processes : Rinse

Benefits

- ✓ Straightforward process
- ✓ Pattern collapse mitigation
- ✓ Defect reduction

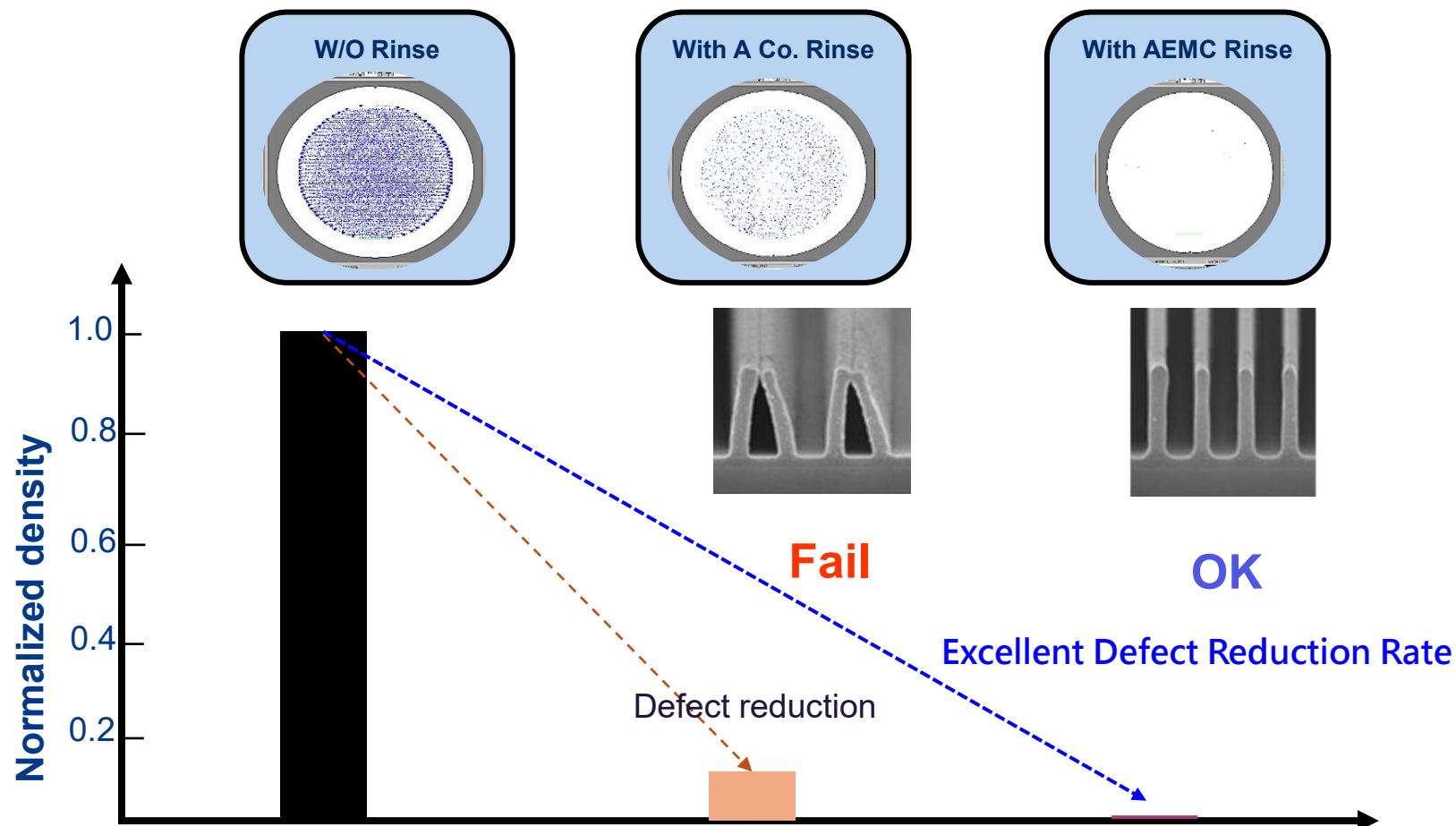
Infusing Professional Resources to Enhance Supplier's R&D Capabilities

Lithography is a critical process in semiconductor manufacturing and is one of the core technologies that ensures chip quality and stability. Due to the high threshold for material research and production technology, the Lithography process has traditionally relied on imported materials. In 2019, in order to enhance the research and development capabilities and production efficiency of the domestic supply chain, TSMC's Material Supply Chain Management (MSCM) collaborated extensively with the Nano Patterning Technology Division (NPTD) to launch the 'Supplier Raw Material Technology Guidance Program'. Offering expert guidance on the seven major aspects of Lithography process materials, including technology development, quality assurance analysis, data calibration, sample verification, factory configuration, tank optimization, and production expansion planning. The program has not only effectively reduced the supplier's line setup and product verification time by 50%, but its material quality also surpasses TSMC's process standards, further improving yield rates and strengthening the competitiveness of the supplier in all aspects. This initiative has laid a solid foundation for the development of the domestic Lithography process material supply chain.



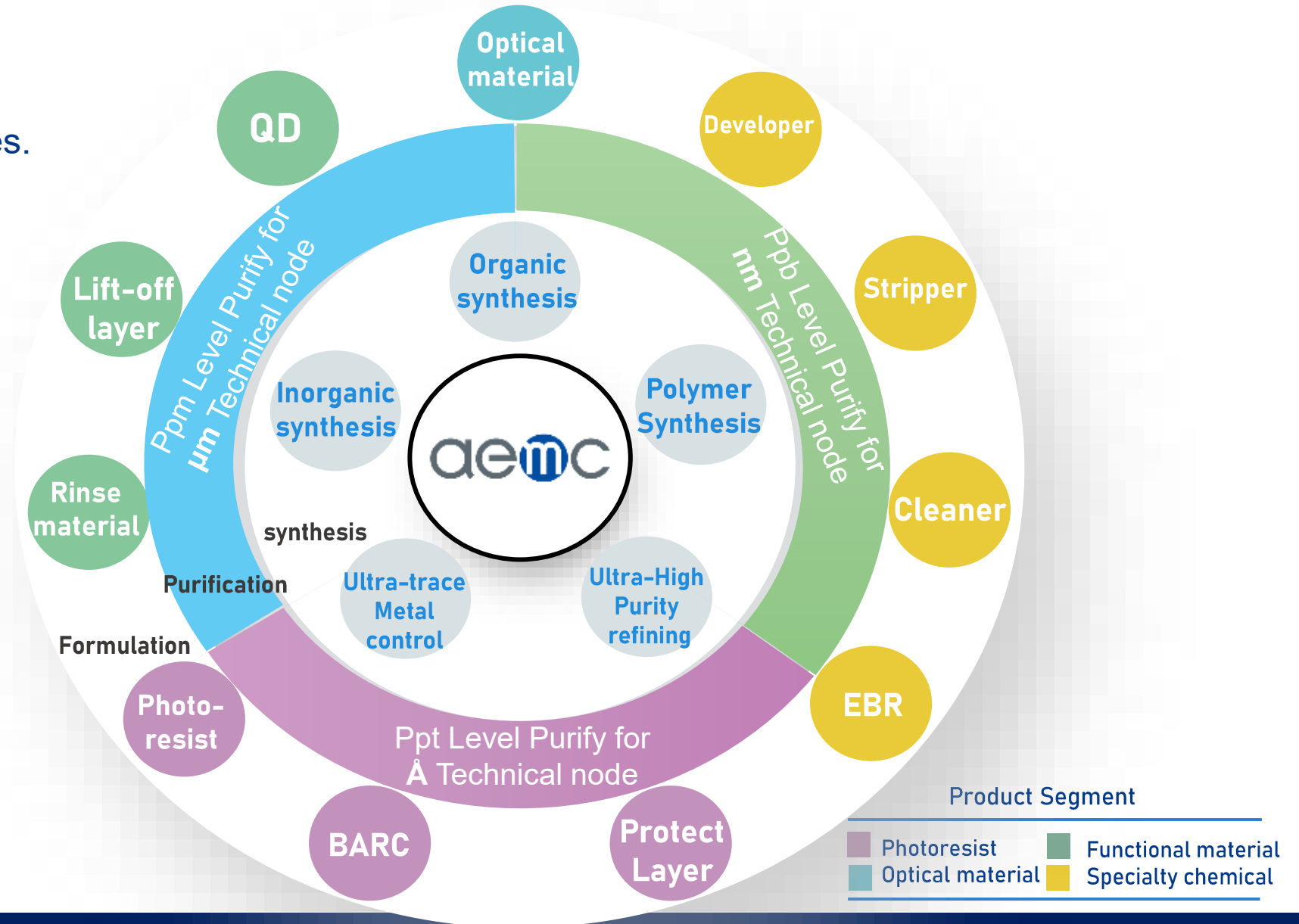
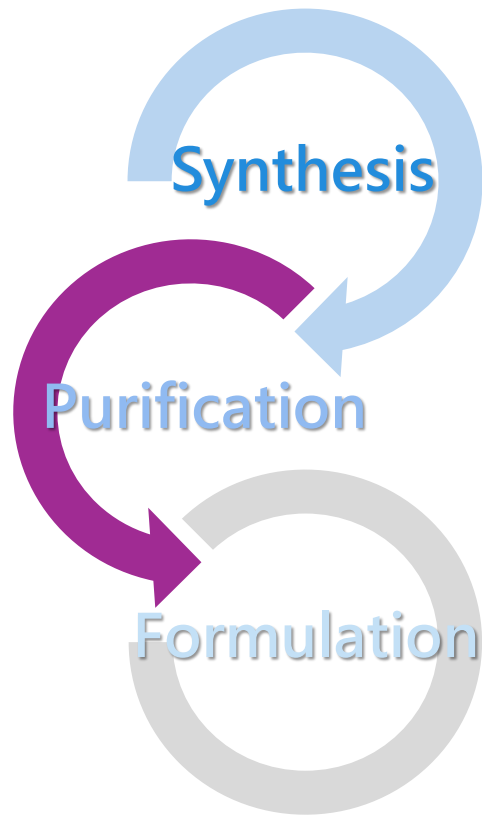
Source: Foundry Customers' ESG Website
<https://esg.tsmc.com/zh-Hant/articles/74>

Defect Comparison:
The performance of AEMC's Rinse materials ranks **No. 1** in the world.

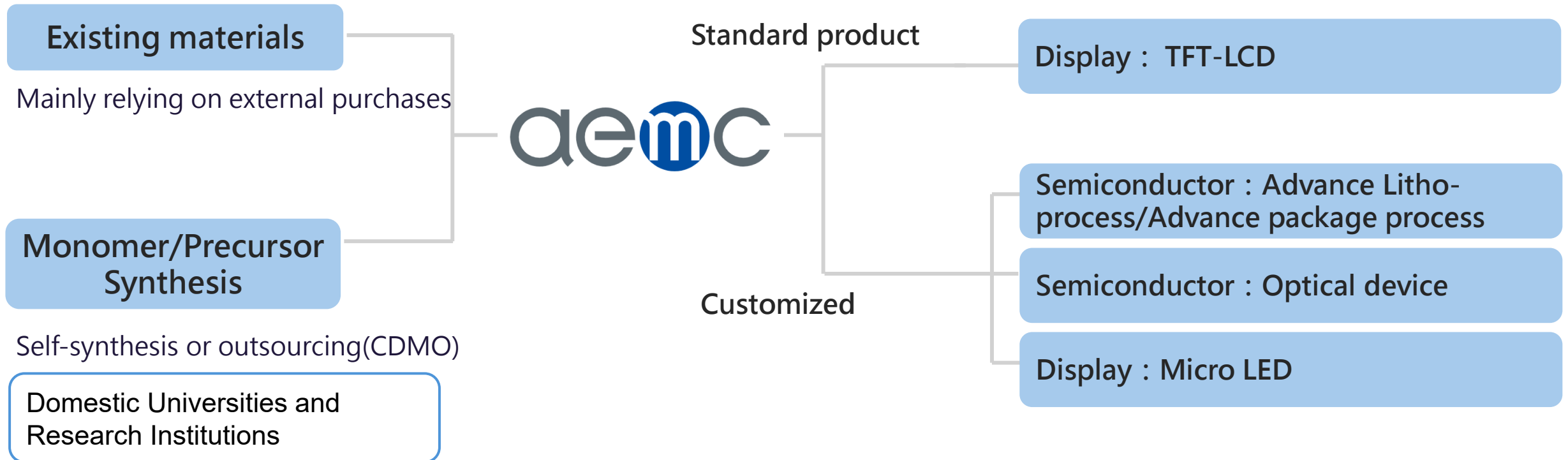


Adv.1. Integrating Upstream From Formulation Technology

20 Years of Materials and
>1,000 Formulations Databases.



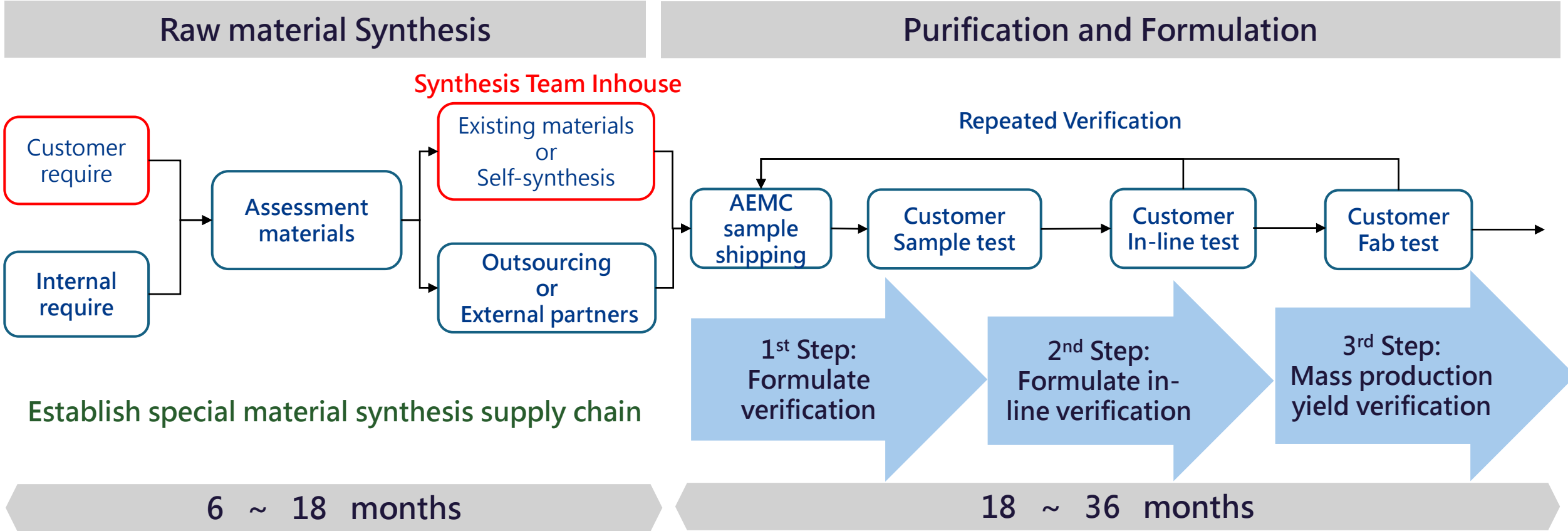
Adv 2. Establishing the Strategic Alliance for TW Material Supply Chain



Adv.3. Fast Response Time and High Learning Curve



Higher response speed / Sample delivery frequency
Customized development

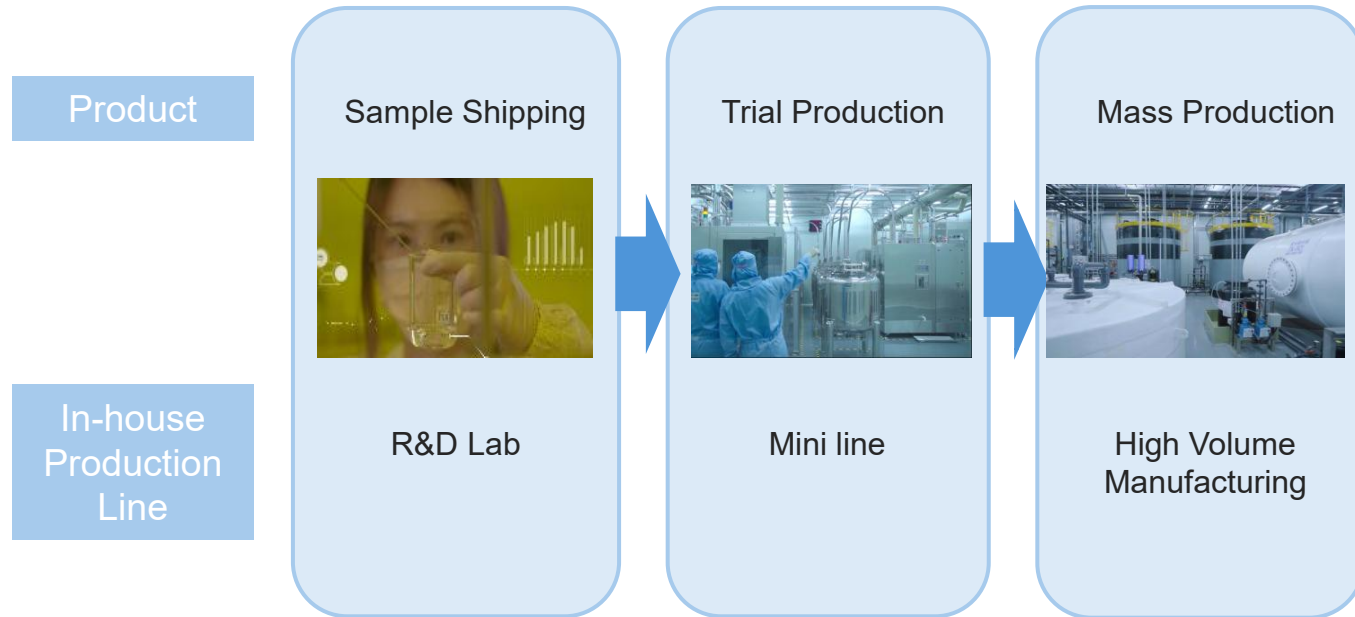


Excellent Quality Control

✓ Quality Control Equipment and Systems:

1. Building Equipment of the Same Level as Customers
2. Ultra-Trace Impurity Control to Meet the Requirements of Advanced Semiconductor Processes: Evolving from ppb (10^{-9}) to ppt (10^{-12}) levels
3. Intelligent Quality Monitoring System: Automated Product Inspection and Integrated Quality Data Analysis

Self Designed Manufacturing Technology



Note: Peer Products Comparison



Mass production V
Under verification O

Litho Process Materials			B*	M*	J*	S*	F*	T*	S*	N*	Q*
		TW	DE	DE	JP	JP	JP	JP	JP	JP	US
Photoresist	CIS	V					V				
	G/I-line	V		V	V	V	V	V	V		
	KrF	O		V	V	V	V	V	V		V
	ArF	O		V	V	V	V	V	V		V
	EUV				V	V		V	V		
Peripheral Materials	BARC	V								V	V
	Rinse	V		V							
	Cleaner	V	V								
	Developer	V						V			
	EBR	V	V	V	V			V			
	Insulation layer materials	O								V	

Note: Compiled by Mega Securities, based on the company's official website and public information.
The materials above focus on the front-end process of semiconductors.